

# BTA40 A/B

# STANDARD TRIACS

#### **FEATURES**

■ HIGH SURGE CURRENT CAPABILITY

■ COMMUTATION: (dV/dt)c>10V/µs

■ BTA Family:

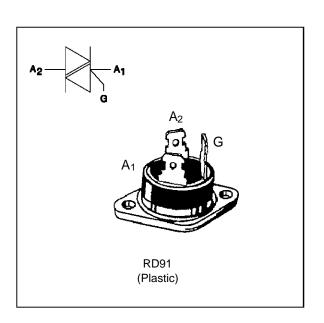
INSULATING VOLTAGE = 2500V<sub>(RMS)</sub>

(UL RECOGNIZED : E81734)

## **DESCRIPTION**

The BTA40 A/B triac family are high performance glass passivated PNPN devices.

These parts are suitables for general purpose applications where high surge current capability is required. Application such as phase control and static switching on inductive or resistive load.



# **ABSOLUTE RATINGS** (limiting values)

Symbol	Parameter	Value	Unit	
lT(RMS)	RMS on-state current (360° conduction angle)	Tc = 75 °C	40	А
ITSM	ITSM Non repetitive surge peak on-state current $(Tj initial = 25^{\circ}C)$ $tp = 8.3 ms$ $tp = 10 ms$		315	А
			300	
l2t	I2t value	tp = 10 ms	450	A2s
dl/dt	Critical rate of rise of on-state current Gate supply: IG = 500mA dig/dt = 1A/μs	Repetitive F = 50 Hz	10	A/μs
		Non Repetitive	50	
Tstg Tj	Storage and operating junction temperature range		- 40 to + 150 - 40 to + 125	°C
TI	Maximum lead temperature for soldering during 1 from case	260	°C	

Symbol	Parameter	BTA40 A/B				
		400	600	700	800	
V <sub>DRM</sub> V <sub>RRM</sub>	Repetitive peak off-state voltage Tj = 125 °C	400	600	700	800	V

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# THERMAL RESISTANCES

Symbol Parameter		Value	Unit
Rth (j-c) DC	Junction to case for DC	1.2	°C/W
Rth (j-c) AC	Junction to case for 360° conduction angle (F= 50 Hz)	0.9	°C/W

# **GATE CHARACTERISTICS** (maximum values)

 $P_{G}$  (AV) = 1W  $P_{GM}$  = 40W (tp = 20  $\mu s$ )  $I_{GM}$  = 8A (tp = 20  $\mu s$ )  $V_{GM}$  = 16V (tp = 20  $\mu s$ ).

# **ELECTRICAL CHARACTERISTICS**

Symbol	Test Conditions		Quadrant		Su	ffix	Unit
					Α	В	
IGT	V <sub>D</sub> =12V (DC) R <sub>L</sub> =33Ω	Tj=25°C	1-11-111	MAX	100	50	mA
			IV	MAX	150	100	
VGT	V <sub>D</sub> =12V (DC) R <sub>L</sub> =33Ω	Tj=25°C	I-II-III-IV	MAX	1.	.5	V
VGD	VD=VDRM RL=3.3kΩ	Tj=125°C	I-II-III-IV	MIN	0.	.2	V
tgt	$VD=VDRM$ $IG = 500mA$ $dI_G/dt = 3A/\mu s$	Tj=25°C	I-II-III-IV	TYP	2	.5	μs
ΙL	I <sub>G</sub> =1.2 I <sub>GT</sub>	Tj=25°C	I-III-IV	TYP	70	60	mA
			Ш		200	180	
I <sub>H</sub> *	I <sub>T</sub> = 500mA gate open	Tj=25°C		MAX	100	80	mA
V <sub>TM</sub> *	I <sub>TM</sub> = 60A tp= 380μs	Tj=25°C		MAX	1.	.8	V
IDRM	V <sub>DRM</sub> Rated	Tj=25°C		MAX	0.0	01	mA
IRRM	VRRM Rated	Tj=125°C		MAX	(	6	
dV/dt *	Linear slope up to V <sub>D</sub> =67%V <sub>DRM</sub> gate open	Tj=125°C		MIN	25	50	V/μs
(dV/dt)c *	(dl/dt)c = 18A/ms	Tj=125°C		MIN	1	0	V/μs

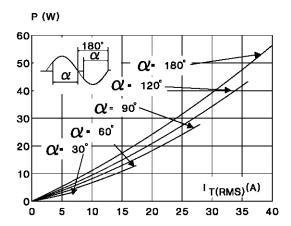
 $<sup>^{\</sup>star}$  For either polarity of electrode A2 voltage with reference to electrode A1.



## ORDERING INFORMATION

Package	IT(RMS)	V <sub>DRM</sub> / V <sub>RRM</sub>	Sensitivity Specification	
	Α	V	Α	В
ВТА	40	400	Х	X
(Insulated)		600	X	X
		700	Х	Х
		800	X	X

**Fig.1**: Maximum RMS power dissipation versus RMS on-state current (F=50Hz). (Curves are cut off by (dl/dt)c limitation)



 $\label{eq:Fig.2:Correlation} \textbf{Fig.2:} Correlation between maximum RMS power dissipation and maximum allowable temperatures ($T_{amb}$ and $T_{case}$) for different thermal resistances heatsink + contact.$ 

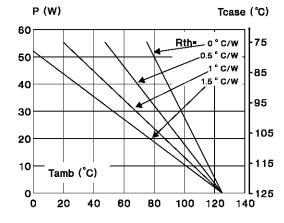
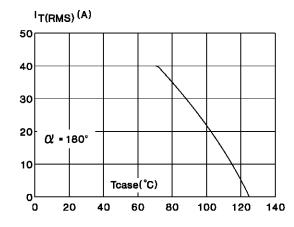


Fig.3: RMS on-state current versus case temperature.



**Fig.4**: relative variation of thermal impedance junction to case versus pulse duration.

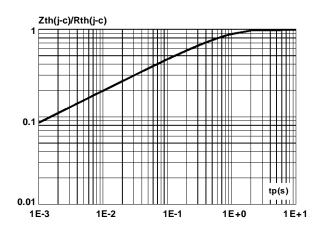


Fig.5: Relative variation of gate trigger current and holding current versus junction temperature.

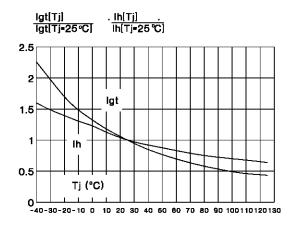


Fig.7 : Non repetitive surge peak on-state current for a sinusoidal pulse with width :  $t \le 10 ms$ , and corresponding value of  $I^2t$ .

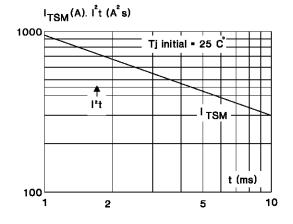


Fig.6: Non Repetitive surge peak on-state current versus number of cycles.

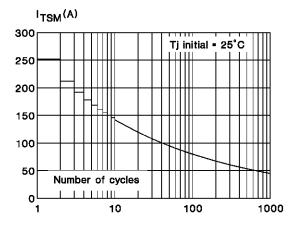
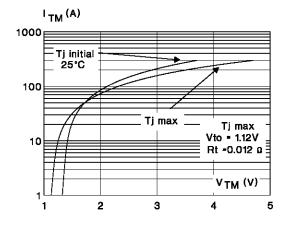
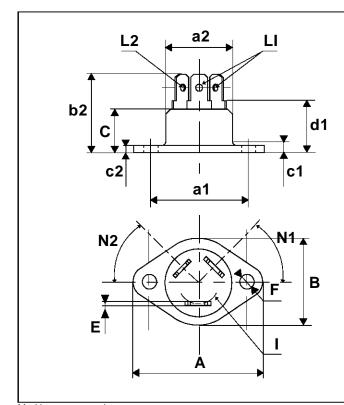


Fig.8 : On-state characteristics (maximum values).



## **PACKAGE MECHANICAL DATA**

RD91 Plastic



REF.	DIMENSIONS				
	Millimeters		Inches		
	Min.	Max.	Min.	Max.	
Α		40.00		1.575	
a1	29.90	30.30	1.177	1.193	
a2		22.00		0.867	
В		27.00		1.063	
b1	13.50	16.50	0.531	0.650	
b2		24.00		0.945	
С		14.00		0.551	
с1		3.50		0.138	
c2	1.95	3.00	0.077	0.118	
E	0.70	0.90	0.027	0.035	
F	4.00	4.50	0.157	0.177	
1	11.20	13.60	0.441	0.535	
L1	3.10	3.50	0.122	0.138	
L2	1.70	1.90	0.067	0.075	
N1	33°	43°	33°	43°	
N2	28°	38°	28°	38°	

Marking : type number Weight : 20 g

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